12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# # 20260327000.0
Qualify additional BOM material for select package devices
Information Only

Date: March 30, 2026
To: MOUSER PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer’s defined process. Customers with previously negotiated special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the Change Management team.

Sincerely,

Change Management Team
SC Business Services

20260327000.0
Information Only
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
UCC21540DWR	595-UCC21540DWR
UCC23511BDWYR	NULL
AMC1100DWVR	AMC1100DWVR
ISO1430DWR	NULL
AMC1306M25DWVR	NULL
AMC1306E25DWVR	NULL
AMC1306M05DWV	NULL
ISO1412BDWR	NULL
UCC23514EDWVR	NULL
AMC1336DWVR	NULL
ISO5451DWR	ISO5451DWR
ISO7821LLSDW	ISO7821LLSDW
AMC1351DWVR	NULL
UCC21540DWKR	NULL
AMC1304L05DW	AMC1304L05DW
AMC1311BDWV	NULL
AMC1350DWV	NULL
UCC21520DWR	UCC21520DWR
AMC1200BDWV	AMC1200BDWV
AMC1302DWVR	NULL
UCC21541DWR	NULL
AMC1305M25DWR	NULL
UCC21520ADWR	UCC21520ADWR
UCC23511DWYR	UCC23511DWYR
UCC23513DWYR	UCC23513DWYR
AMC1350DWVR	NULL
AMC1300DWV	AMC1300DWV
AMC1301DWV	AMC1301DWV
AMC1311DWV	AMC1311DWV
AMC1202DWVR	NULL
ISO1452DWR	595-ISO1452DWR
ISO7821DW	ISO7821DW
UCC23313BDWYR	NULL
UCC23513BDWYR	NULL
AMC1303M2520DWVR	NULL
AMC1306M05DWVR	NULL
AMC1333M10DWVR	NULL
UCC23113DWYR	NULL
ISO5852SDWR	ISO5852SDWR
UCC5350MCDWVR	UCC5350MCDWVR
ISO1452DW	ISO1452DW
AMC1304L25DW	AMC1304L25DW
AMC1305L25DW	AMC1305L25DW
AMC1204BDWV	AMC1204BDWV
AMC1204DW	AMC1204DW
ISO1432BDWR	ISO1432BDWR
AMC1311BDWVR	NULL

UCC21750DWR	UCC21750DWR
UCC5304DWVR	NULL
UCC23514MDWVR	NULL
ISO7842DW	ISO7842DW
AMC1351DWV	NULL
AMC1304M05DW	AMC1304M05DW
ISO224BDWVR	NULL
AMC1300BDWVR	NULL
ISO5452DWR	ISO5452DWR
ISO1430BDWR	ISO1430BDWR
AMC1301DWVR	AMC1301DWVR
AMC1311DWVR	AMC1311DWVR
UCC21540ADWKR	UCC21540ADWKR
ISO1432DW	ISO1432DW
ISO1412DWR	NULL
UCC5310MCDWVR	UCC5310MCDWVR
UCC5390ECDWVR	UCC5390ECDWVR
ISO224ADWVR	NULL
UCC21521DWR	UCC21521DWR
UCC21540ADWR	NULL
UCC21710DWR	NULL
ISO1410DWR	NULL
UCC23313DWYR	UCC23313DWYR

Technical details of this Product Change follow on the next page(s).

Notification Number:	20260327000.0	**Notification Date:**	March 30, 2026
Title:	Qualify additional BOM material for select package devices		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	April 30, 2026	**Sample requests accepted until:**	N/A

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Materials
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments is pleased to announce the qualification of additional BOM material for select devices in the SOIC package. Device affected will remain on current Assembly & Test sites. Material differences as follows.

	Current	**Additional**
Mold compound	4221499-0008 (Hitachi)	4221499-1008 (Sumitomo)

Reason for Change:

Continuity of supply.
Both the current material and the additional material use the same TI material property specification.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

Review the SDP for full evaluation of the change based on the customer use case.

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If the boxes below are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this notification:

None.

Product Affected:

AMC1100DWVR	AMC1306M05DWV	TLA7001DWVR
AMC1106E05DWV	AMC1306M05DWVR	TLA7002DWVR
AMC1106E05DWVR	AMC1306M25DWV	TLA7312DWVR
AMC1106M05DWV	AMC1306M25DWV	TLA8062DWVR
AMC1106M05DWVR	AMC1306M25DWVR	UCC20520DW
AMC1200BDWV	AMC1306M25EDWVR	UCC20520DWR
AMC1202DWVR	AMC1307M05DWR	UCC20520DWR
AMC1204BDW	AMC1311BDWV	UCC21520ADW

AMC1204BDWR	AMC1311BDWV	UCC21520ADWR
AMC1204BDWV	AMC1311BDWVR	UCC21520DWR
AMC1204DW	AMC1311DWV	UCC21520DWR
AMC1204DW	AMC1311DWVR	UCC21521ADW
AMC1204DWR	AMC1333M10DWVR	UCC21521ADWR
AMC1290DWV	AMC1336DWV	UCC21521CDW
AMC1290DWVR	AMC1336DWV	UCC21521CDWR
AMC1300BDWV	AMC1336DWVR	UCC21521CDWR
AMC1300BDWVR	AMC1350DWV	UCC21521DW
AMC1300DWV	AMC1350DWVR	UCC21521DWR
AMC1300DWV	AMC1351DWV	UCC21540ADWKR
AMC1300DWVR	AMC1351DWVR	UCC21540ADWR
AMC1301DWV	ISO1042DWV	UCC21540DW
AMC1301DWV	ISO1410BDW	UCC21540DWK
AMC1301DWVR	ISO1410DW	UCC21540DWKR
AMC1301SDWV	ISO1410DW	UCC21540DWR
AMC1301SDWVR	ISO1410DWR	UCC21541DWR
AMC1302DWV	ISO1412BDW	UCC21542ADWKR
AMC1302DWV	ISO1412BDWR	UCC21542DWKR
AMC1302DWVR	ISO1412DW	UCC21542DWR
AMC1303E0510DWVR	ISO1412DW	UCC21710DW
AMC1303E0520DWVR	ISO1412DWR	UCC21710DWR
AMC1303E2510DWV	ISO1430BDWR	UCC21732DW
AMC1303E2510DWVR	ISO1430DW	UCC21732DWR
AMC1303E2520DWVR	ISO1430DWR	UCC21750DW
AMC1303M0510DWVR	ISO1432BDWR	UCC21750DWR
AMC1303M0520DWVR	ISO1432DW	UCC21750DWR
AMC1303M2510DWVR	ISO1432DWR	UCC23113DWYR
AMC1303M2520DWV	ISO1450DW	UCC23313BDWYR
AMC1303M2520DWVR	ISO1450DWR	UCC23313DWY
AMC1304L05DW	ISO1452DW	UCC23313DWYR
AMC1304L05DWR	ISO1452DWR	UCC23511BDWYR
AMC1304L25DW	ISO224ADWV	UCC23511DWYR
AMC1304L25DWR	ISO224ADWVR	UCC23513BDWYR
AMC1304M05DW	ISO224BDWV	UCC23513DWYR
AMC1304M05DWR	ISO224BDWV	UCC23513DWYR.A
AMC1304M25DW	ISO224BDWVR	UCC23513HDWYR
AMC1304M25DWR	ISO5451DWR	UCC23514EDWVR
AMC1305F25DW	ISO5452DWR	UCC23514MDWVR
AMC1305F25DWR	ISO5851DWR	UCC23514MDWVR
AMC1305L25DW	ISO5852SDWR	UCC23514SDWVR
AMC1305L25DW	ISO7821DW	UCC23514VDWVR
AMC1305L25DWR	ISO7821LLDW	UCC5304DWVR
AMC1305M05DW	ISO7821LLSDW	UCC5304DWVR
AMC1305M05DWR	ISO7842DW	UCC5310MCDWV
AMC1305M25DW	SN2004048DWVR	UCC5310MCDWVR
AMC1305M25DWR	SN201811022DWVR	UCC5320SCDWV

AMC1306E05DWV	SN201811023DWVR	UCC5350MCDWV
AMC1306E05DWVR	SN23511DWYR	UCC5350MCDWVR
AMC1306E25DWV	SN23513DWYR	UCC5390ECDWV
AMC1306E25DWVR	SN5452DWR	UCC5390ECDWVR

Qualification Data

Automotive Qualification Summary
(As per AEC-Q100 Rev. J and JEDEC Guidelines)

MLA Mold Compound change for HPA07ISO, ISO1, ISO2
Approve Date 22-January-2026

Product Attributes

Attributes	Qual Device: AMC1305M25DWQ1-ASY	Qual Device: ISO7763FQDWRQ1	Qual Device: ISO5852SQDWQ1	Qual Device: AMC1311QDWVRQ1	QBS Process Reference: ISO6441FDWRQ1	QBS Package Reference: UCC21551CQDFJRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	ASIC	Power Management	Power Management	Power Management	Interface	Power Management
Wafer Fab Supplier	DP1DM5, DP1DM5, AIZU	RFAB, RFAB	DP1DM5, DP1DM5, MH8	AIZU, AIZU, MH8, MH8	RFAB, RFAB, MH8	RFAB, RFAB, RFAB
Assembly Site	MLA	MLA	MLA	MLA	MLA	MLA
Package Group	SOIC	SOIC	SOIC	SOIC	SOIC	SSOP
Package Designator	DWV	DW	DW	DWV	DW	DFJ
Pin Count	16	16	16	8	16	28

QBS: Qual By Similarity, also known as Generic Data
Qual Device AMC1305M25DWQ1-ASY is qualified at MSL3 260C
Qual Device ISO7763FQDWRQ1 is qualified at MSL2 260C
Qual Device UCC21710QDWQ1 is qualified at MSL3 260C
Qual Device ISO5852SQDWQ1 is qualified at MSL2 260C
Qual Device AMC1311QDWVRQ1 is qualified at MSL3 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: AMC1305M25DWQ1-ASY	Qual Device: ISO7763FQDWRQ1	Qual Device: ISO5852SQDWQ1	Qual Device: AMC1311QDWVRQ1	QBS Process Reference: ISO6441FDWRQ1	QBS Package Reference: UCC21551CQDFJRQ1
Test Group A - Accelerated Environment Stress Tests													
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	-	-	No Fails	-	No Fails	No Fails
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-	1/77/0	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-	-	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	1/77/0	-
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	-	1/77/0	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	-	-	1/5/0	-	1/5/0	1/5/0
TC-SAM	A4	-	3	3	Post TC SAM	<50% delamination	-	-	-	3/36/0	-	1/12/0	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	-	1/45/0	3/231/0
Test Group B - Accelerated Lifetime Simulation Tests													
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	-	-	-	1/77/0	-

Test Group C - Package Assembly Integrity Tests													
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0	3/90/0	-	1/30/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0	3/90/0	-	1/30/0
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-	-	-	1/15/0	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	3/30/0	3/30/0	3/30/0	3/30/0	-	1/10/0
Test Group D - Die Fabrication Reliability Tests													
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests													
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	-	-	1/3/0	-	-	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	-	-	1/3/0	-	-	-
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	-	-	1/3/0	-	-	-
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	-	1/30/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C
Grade 1 (or Q): -40C to +125C
Grade 2 (or T): -40C to +105C
Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2310-111

Qualification Data

Automotive Qualification Summary

(As per AEC-Q100 Rev. J and JEDEC Guidelines)

TITL Mold Compound change for HPA07ISO, ISO1, ISO2
Approve Date 09-October-2025

Product Attributes

Attributes	Qual Device: ISO1410DWR	QBS Process Reference: ISO5851QDWQ1	QBS Package Reference: ISOUSB211DPRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125
Product Function	Power Management	Interface	Interface
Wafer Fab Supplier	MH8, MH8, MH8	MH8, DP1DM5, DP1DM5	MH8, MH8, RFAB, RFAB, MH8, MH8
Assembly Site	TAI	TAI	TAI
Package Group	SOIC	SOIC	SSOP
Package Designator	DW	DW	DP
Pin Count	16	16	28

QBS: Qual By Similarity, also known as Generic Data
Qual Device ISO1410DWR is qualified at MSL2 260C
Qual Device UCC5871QDWJRQ1 is qualified at MSL3 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: ISO1410DWR	QBS Process Reference: ISO5851QDWQ1	QBS Package Reference: ISOUSB211DPRQ1
Test Group A - Accelerated Environment Stress Tests										
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	No Fails	-	No Fails
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	3/231/0	-	3/231/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	-	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	-	-	1/5/0
TC-SAM	A4	-	3	3	Post TC SAM	<50% delamination	-	-	-	3/36/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0
Test Group B - Accelerated Lifetime Simulation Tests										
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	3/231/0	1/77/0
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-
Test Group C - Package Assembly Integrity Tests										
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	-	3/90/0

WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	-	3/90/0
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	3/30/0	-	3/30/0
Test Group D - Die Fabrication Reliability Tests										
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests										
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	-	1/3/0	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	-	1/3/0	-
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	-	1/6/0	-
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	1/30/0	-

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Ambient Operating Temperature by Automotive Grade Level:
Grade 0 (or E): -40C to +150C
Grade 1 (or Q): -40C to +125C
Grade 2 (or T): -40C to +105C
Grade 3 (or I) : -40C to +85C
E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):
Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
Room : AC/uHAST
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2503-064

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic

(family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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